

Project Information

Reference
Date

Construction Type

Element	: Solid ground floor - 15.01.26 - Floor - Solid Ground (Floating Floor, Chipboard) - SFUF 110mm PIR - 0.13					
Internal surface emissivity	: High	External surface emissivity		: High		
		Thickness	Thermal Conductivity	Thermal Resistance	Pitch	Bridge details
		(mm)	(W/mK)	(m²K/W)	(°)	Air gaps (Level, Delta U")
Inside surface		-	-	0.170		
Rapid Response Board		20.0	0.130	0.154		
Rigid Insulation Board		110.0	0.022	5.000		L:0 0.000W/m²K
SuperFOIL SFUF		6.0	-	0.800		
Medium density (2000 kg/m3) concrete		150.0	1.350	0.112		
Ground		-	-	0.040		
Total thickness		286.0mm				

Ground Floor Details

Floor type	: Solid floor			
Calculation method	: EN ISO 13370:2007			
Perimeter	: 38.00 m	Area	: 70.00 m²	
P/A	: 0.543	Characteristic dimension, B'	: 3.684	
Thermal conductivity of ground:	: 1.500 W/mK	Width of walls, w:	: 0.300 m	
Edge insulation position	: None			

U-value = 0.13W/m²K

U-value, Combined Method : 0.132W/m²K (upper/lower limit 6.276 / 6.276m²K/W, dUf 0.0000, dUg 0.0000, dUp 0.0000, dUr 0.0000, dUrc1 0.0000, dUrc2 0.0000)

Correction factors

Air gaps, Delta Ug = 0.000W/m²K

This free U-value calculation is based on recipient-provided information. Every effort has been made to ensure accuracy, but Boulder Developments Ltd and associated parties are not liable. Project management and building control authorities must approve the specification. It demonstrates only the thermal transmittance of the specified construction. Other building regulation compliances, including fire safety, must be independently assessed.